#### PATENT ASSIGNMENT

## Electronic Version v1.1 Stylesheet Version v1.1

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

#### **CONVEYING PARTY DATA**

Name	Execution Date
Griselda Bonilla	10/29/2009
Kaushik Chanda	11/02/2009
Ronald G. Filippi	10/20/2009
Stephan Grunow	11/02/2009
David L. Rath	10/23/2009
Sujatha Sankaran	11/05/2009
Andrew H. Simon	10/21/2009
Theodorus E. Standaert	10/20/2009
Chih-Chao Yang	10/20/2009

#### **RECEIVING PARTY DATA**

Name:	International Business Machines Corporation	
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City:	Armonk	
State/Country:	NEW YORK	
Postal Code:	10504	

### PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	12613551

#### **CORRESPONDENCE DATA**

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PATENT

REEL: 023513 FRAME: 0887

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ATTORNEY DOCKET NUMBER: FIS920090063US1	
NAME OF SUBMITTER:	Yuanmin Cai
Total Attachments: 9 source=FIS920090063US1_SIGNEDASSIGNMENT#page1.tif source=FIS920090063US1_SIGNEDASSIGNMENT#page2.tif source=FIS920090063US1_SIGNEDASSIGNMENT#page3.tif source=FIS920090063US1_SIGNEDASSIGNMENT#page4.tif source=FIS920090063US1_SIGNEDASSIGNMENT#page5.tif source=FIS920090063US1_SIGNEDASSIGNMENT#page6.tif source=FIS920090063US1_SIGNEDASSIGNMENT#page7.tif source=FIS920090063US1_SIGNEDASSIGNMENT#page8.tif source=FIS920090063US1_SIGNEDASSIGNMENT#page8.tif source=FIS920090063US1_SIGNEDASSIGNMENT#page9.tif	

PATENT REEL: 023513 FRAME: 0888

#### **ASSIGNMENT**

Whereas, the undersigned Inventor(s) has/have made certain inventions, improvements, and discoveries (herein referred to as the "Invention") in:

Title of the Invention: IMPROVED CAPPING OF COPPER INTERCONNECT LINES IN INTEGRATED CIRCUIT DEVICES

and further identified by the IBM Docket Number provided above in the header of this Assignment, for which an application for a United States Patent was executed concurrently herewith or was filed having		
Serial Number:	(insert series code and serial number here if/when available	
business at Armonk, New York (1	Machines Corporation, a corporation of New York having a place of herein referred to as "IBM"), desires to acquire, and each undersigned the entire worldwide right, title, and interest in and to the Invention and	

in and to any and all patent applications and patents directed thereto:

Now, therefore, for good and valuable consideration, the receipt and sufficiency thereof being hereby acknowledged, each undersigned Inventor ("ASSIGNOR") hereby sells, assigns, and otherwise transfers to IBM (the "ASSIGNEE"), its successors, legal representatives, and assigns, the entire worldwide right, title, and interest in and to the Invention, the above-identified United States patent application, and any and all other patent applications and patents for the Invention which may be applied for or granted therefor in the United States and in all foreign countries and jurisdictions, including all divisions, continuations, reissues, reexaminations, renewals, extensions, counterparts, substitutes, and extensions thereof, and all rights of priority resulting from the filing of such applications and granting of such patents. In addition, each undersigned Inventor hereby authorizes and requests the Director of the United States Patent and Trademark Office to issue any United States Patent, and foreign patent authorities to issue any foreign patent, granted for the Invention, to IBM, its successors, legal representatives, and assigns, the entire worldwide right, title, and interest in and to the same to be held and enjoyed by IBM, its successors, legal representatives, and assigns to the full end of the terms for which any and all such patents may be granted, as fully and entirely as would have been held and enjoyed by the undersigned had this Assignment not been made; and each undersigned Inventor agrees to execute any and all documents and instruments and perform all lawful acts reasonably related to recording this Assignment or perfecting title to the Invention and all related patents and applications, in IBM, its successors, legal representatives, and assigns, whenever requested by IBM, its successors, legal representatives, or assigns.

Each undersigned Inventor acknowledges their prior and ongoing obligations to sell, assign, and transfer the rights under this Assignment to IBM and is unaware of any reason why they may not have the full and unencumbered right to sell, assign, and transfer the rights hereby sold, assigned, and transferred, and has not executed, and will not execute, any document or instrument in conflict herewith. Each undersigned Inventor also hereby grants IBM, its successors, legal representatives, and assigns, the right to insert in this Assignment any further identification (including, but not limited to, patent application Serial Number) which may be necessary or desirable for recordation of this Assignment. This Assignment is governed by the substantive laws of the State of New York, and any disputes will be resolved in a New York state court or federal court sited in New York.

[Inventor Signature Page(s) Follows]

***************************************		Executed by Inventor 1
Signature:	Griselda Bonilla	Date: 10/29/2009
V <sup>N</sup> 4 d MM (State of the State		Executed by Inventor 2
Signature: _	Kaushik Chanda	Date:
		Executed by Inventor 3
Signature: _	Ronald G. Filippi	Date:
		Executed by Inventor 4
Signature: _	Stephan Grunow	Date:
The second secon		Executed by Inventor 5
Signature: _	David L. Rath	Date:

Page 2 of 3

***************************************	Executed by Inventor 6	
Signature: _	Sujatha Sankaran	
Activity of the State of the St	Executed by Inventor 7	
Signature:	Date:Date:	
-	Executed by Inventor 8	Name of the last section o
Signature:	Theodorus E. Standaert	
	Executed by Inventor 9	
Signature:	Chih-Chao Yang	

Page 3 of 3

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Serial Number:	(insert series code and serial number here if/when available)
Whereas, International Business business at Armonk, New York	ss Machines Corporation, a corporation of New York having a place of the characteristic (herein referred to as "IBM"), desires to acquire, and each undersigned
Inventor desires to grant to IBN	M, the entire worldwide right, title, and interest in and to the Invention and dications and patents directed thereto;

Now, therefore, for good and valuable consideration, the receipt and sufficiency thereof being hereby acknowledged, each undersigned Inventor ("ASSIGNOR") hereby sells, assigns, and otherwise transfers to IBM (the "ASSIGNEE"), its successors, legal representatives, and assigns, the entire worldwide right, title, and interest in and to the Invention, the above-identified United States patent application, and any and all other patent applications and patents for the Invention which may be applied for or granted therefor in the United States and in all foreign countries and jurisdictions, including all divisions, continuations, reissues, reexaminations, renewals, extensions, counterparts, substitutes, and extensions thereof, and all rights of priority resulting from the filing of such applications and granting of such patents. In addition, each undersigned Inventor hereby authorizes and requests the Director of the United States Patent and Trademark Office to issue any United States Patent, and foreign patent authorities to issue any foreign patent, granted for the Invention, to IBM, its successors, legal representatives, and assigns, the entire worldwide right, title, and interest in and to the same to be held and enjoyed by IBM, its successors, legal representatives, and assigns to the full end of the terms for which any and all such patents may be granted, as fully and entirely as would have been held and enjoyed by the undersigned had this Assignment not been made; and each undersigned Inventor agrees to execute any and all documents and instruments and perform all lawful acts reasonably related to recording this Assignment or perfecting title to the Invention and all related patents and applications, in IBM, its successors, legal representatives, and assigns, whenever requested by IBM, its successors, legal representatives, or assigns.

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[Inventor Signature Page(s) Follows]

Executed by Inventor 1		
Signature: _	Griselda Bonilla	Date:
	Executed by Inventor	r 2
Signature: _	Kaushik Chanda	Date:
***************************************	Executed by Inventor	• 3
Signature: _	Ronald G. Filippi	Date: 10/20/09
	Executed by Inventor	· 4
Signature: _	Stephan Grunow	Date: 11/2/09
	Executed by Inventor	•5
Signature: _	David L. Rath	Date: 10/23/09

Page 2 of 3

Executed by Inventor 6		
Signature:	Sujatha Sankaran	Date:/5/09
	Executed by I	Inventor 7
Signature: _	Andrew H. Simon	
	Executed by I	inventor 8
Signature:	Theodorus E. Standaert	Date:
	Executed by I	nventor 9
Signature:	Chih-Chao Yang	Date:

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		Executed by Inventor 4	
Signature:	Stephan Grunow	Date:	
		Executed by Inventor 5	
Signature:	Desid I Bak	Date:	

Page 2 of 3

	Executed by Inventor 6
Signature: _	Date: Sujatha Sankaran
	Executed by Inventor 7
Signature: _	Date: Andrew H. Simon
	Executed by Inventor 8
Signature: _	Theodorus E. Standaert  Date: 10/20/2009
W. M.L.	Executed by Inventor 9
Signature:	Chih-Chao Yang Date: 10/20/2009

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